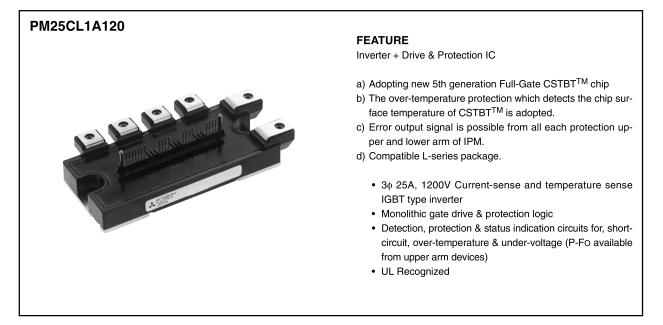
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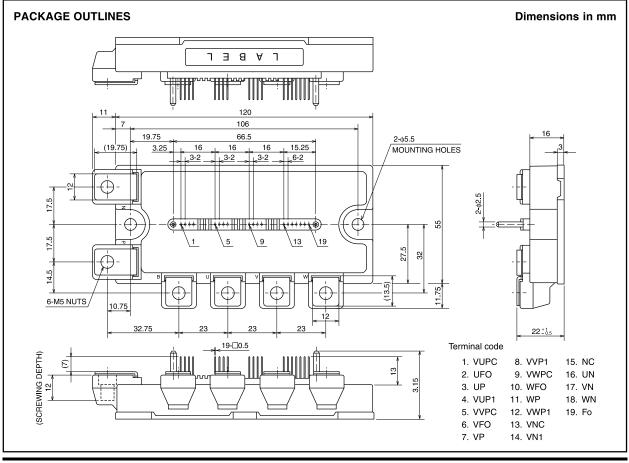
PM25CL1A120

FLAT-BASE TYPE INSULATED PACKAGE



APPLICATION

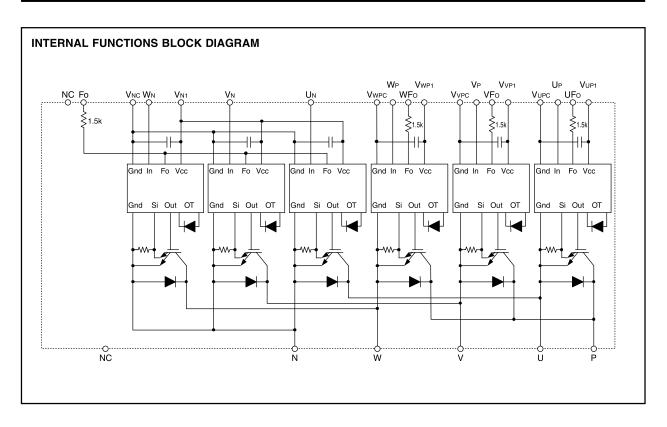
General purpose inverter, servo drives and other motor controls





May 2009

FLAT-BASE TYPE INSULATED PACKAGE



MAXIMUM RATINGS (Tj = 25° C, unless otherwise noted) **INVERTER PART**

Symbol	Parameter	Condition		Ratings	Unit
VCES	Collector-Emitter Voltage	VD = 15V, VCIN = 15V		1200	V
±lc	Collector Current	Tc = 25°C	(Note-1)	25	Α
±IСР	Collector Current (Peak)	Tc = 25°C		50	Α
Pc	Collector Dissipation	Tc = 25°C	(Note-1)	128	W
Tj	Junction Temperature			-20 ~ +150	°C

*: Tc measurement point is just under the chip.

CONTROL PART

Symbol	Parameter	Condition	Ratings	Unit
VD	Supply Voltage	Applied between : VUP1-VUPC, VVP1-VVPC VWP1-VWPC, VN1-VNC	20	v
VCIN	Input Voltage	Applied between : UP-VUPC, VP-VVPC, WP-VWPC UN • VN • WN-VNC	20	v
VFO	Fault Output Supply Voltage	Applied between : UFO-VUPC, VFO-VVPC, WFO-VWPC FO-VNC	20	V
IFO	Fault Output Current	Sink current at UFO, VFO, WFO, FO terminals	20	mA



4.8

PM25CL1A120

FLAT-BASE TYPE **INSULATED PACKAGE**

TOTAL SYSTEM

Symbol	Parameter	Condition	Ratings	Unit
VCC(PROT)	Supply Voltage Protected by SC	$V_D = 13.5 \sim 16.5V$ Inverter Part, Tj = +125°C Start	800	v
VCC(surge)	Supply Voltage (Surge)	Applied between : P-N, Surge value	1000	V
Tstg	Storage Temperature		-40 ~ +125	°C
Viso	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base, AC 1 min.	2500	Vrms

THERMAL RESISTANCES

-7.0

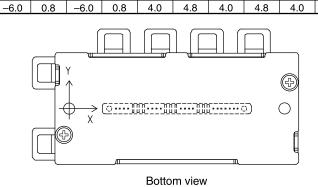
Υ

-0.2

		Condition		Limits			
Symbol	Parameter			Тур.	Max.	Unit	
Rth(j-c)Q	Junction to case Thermal	Inverter IGBT part (per 1 element) (Note	1)	_	0.97		
Rth(j-c)F	Resistances	Inverter FWDi part (per 1 element) (Note	1)	_	1.60	∘c/w	
	Contact Thermal Resistance	Case to fin, (per 1 module)			0.038	°C/w	
Rth(c-f)		Thermal grease applied (Note	1)	_			

* If you use this value, Rth(f-a) should be measured just under the chips.

(Note-1) Tc (under the chip) measurement point is below. (unit : mm)													
Γ	arm	U	Р	V	Р	N	/P	U	N	V	N	W	'N
1	axis	IGBT	FWDi										
	x	27.0	27.0	66.9	66.9	86.5	86.5	39.2	33.2	54.3	60.7	73.9	80.3



ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise noted) **INVERTER PART**

O maked by Development		Condii	Condition			Unit		
Symbol	Parameter	Condi	uon		Min.	Тур.	Max.	Onit
Varia	Collector-Emitter Saturation	VD = 15V, IC = 25A		Tj = 25°C	-	1.65	2.15	. v
VCE(sat)	Voltage	VCIN = 0V, Pulsed	(Fig. 1)	Tj = 125°C	—	1.85	2.35	V
VEC	FWDi Forward Voltage	-IC = 25A, VD = 15V, VCIN = -	15V	(Fig. 2)	-	2.3	3.3	V
ton					0.3	0.8	2.0	
trr		$VD = 15V, VCIN = 0V \leftrightarrow 15V$			—	0.3	0.8	
tc(on)	Switching Time	Vcc = 600V, Ic = 25A			—	0.4	1.0	μs
toff		Tj = 125°C		(Eim 0.4)	_	1.2	2.8	
tc(off)		Inductive Load		(Fig. 3,4)		0.4	1.2	
1050	Collector-Emitter Cutoff		([]~ [)	Tj = 25°C		_	1	
ICES	Current	VCE = VCES, VD = 15V	(Fig. 5)	Tj = 125°C	_	_	10	mA



FLAT-BASE TYPE INSULATED PACKAGE

CONTROL PART

Symbol		O a se altàtica se					
Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit	
ID	Circuit Current	VD = 15V, VCIN = 15V	VN1-VNC	—	6	12	mA
		VD = 15V, VCIN = 15V	V*P1-V*PC	_	2	4	ma
Vth(ON)	Input ON Threshold Voltage	Applied between : UP-VUPC, VP-VVPC,	WP-VWPC	1.2	1.5	1.8	v
Vth(OFF)	Input OFF Threshold Voltage	UN • VN • WN-VNC		1.7	2.0	2.3	v
SC	Short Circuit Trip Level	$-20 \leq T_j \leq 125^\circ C, \ VD = 15V$	(Fig. 3,6)	50	_	_	A
toff(SC)	Short Circuit Current Delay Time	VD = 15V	(Fig. 3,6)	_	0.2	_	μs
ОТ	Quer Temperature Drotection	Detect Temperature of IGBT chip	Trip level	135	_		°C
OT(hys)	Over Temperature Protection		Hysteresis	_	20		
UV	Supply Circuit Under-Voltage	–20 ≤ Ti ≤ 125°C	Trip level	11.5	12.0	12.5	v
UVr	Protection	$-20 \leq 1 \leq 123 C$	Reset level	_	12.5		v
IFO(H)	Fault Output Current	VD = 15V, VCIN = 15V	(Note-2)		—	0.01	mA
IFO(L)		VD = 15V, VCIN = 15V	(11016-2)	_	10	15	
tFO	Minimum Fault Output Pulse Width	VD = 15V	(Note-2)	1.0	1.8	_	ms

(Note-2) Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

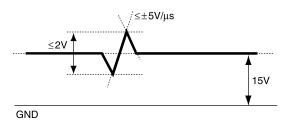
MECHANICAL RATINGS AND CHARACTERISTICS

	D	Condition		Unit			
Symbol	Parameter	Condition		Min.	Тур.	Max.	
	Mounting torque	Mounting part scre	ew : M5	2.5	3.0	3.5	N • m
		Main terminal part scre	ew : M5	2.5	3.0	3.5	N•m
_	Weight	—		—	380	—	g

RECOMMENDED CONDITIONS FOR USE

Symbol	Parameter	Condition	Recommended value	Unit
Vcc	Supply Voltage	Applied across P-N terminals	≤ 800	V
VD	Control Supply Voltage	Applied between : VUP1-VUPC, VVP1-VVPC VWP1-VWPC, VN1-VNC (Note-3)	15.0 ± 1.5	v
VCIN(ON)	Input ON Voltage	Applied between : UP-VUPC, VP-VVPC, WP-VWPC	≤ 0.8	v
VCIN(OFF)	Input OFF Voltage	UN • VN • WN-VNC	≥ 9.0	7 °
fpwm	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
tdead	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig. 7)	≥ 2.5	μs

(Note-3) With ripple satisfying the following conditions: dv/dt swing $\leq \pm 5V/\mu s$, Variation $\leq 2V$ peak to peak



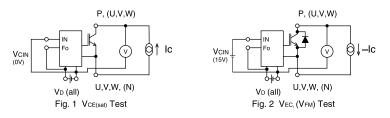


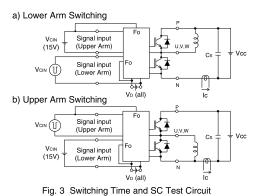
FLAT-BASE TYPE INSULATED PACKAGE

PRECAUTIONS FOR TESTING

- Before applying any control supply voltage (VD), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.
 After this the specified ON and OFF level setting for each input signal should be done.
- After this, the specified ON and OFF level setting for each input signal should be done.
- 2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above VCEs rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)





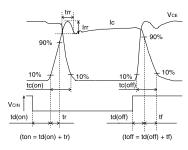
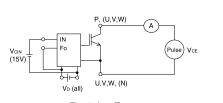
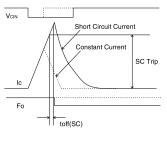


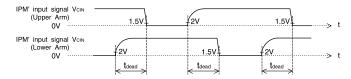
Fig. 4 Switching Time Test Waveform











1.5V: Input on threshold voltage Vth(on) typical value, 2V: Input off threshold voltage Vth(off) typical value

Fig. 7 Dead time measurement point example



FLAT-BASE TYPE INSULATED PACKAGE

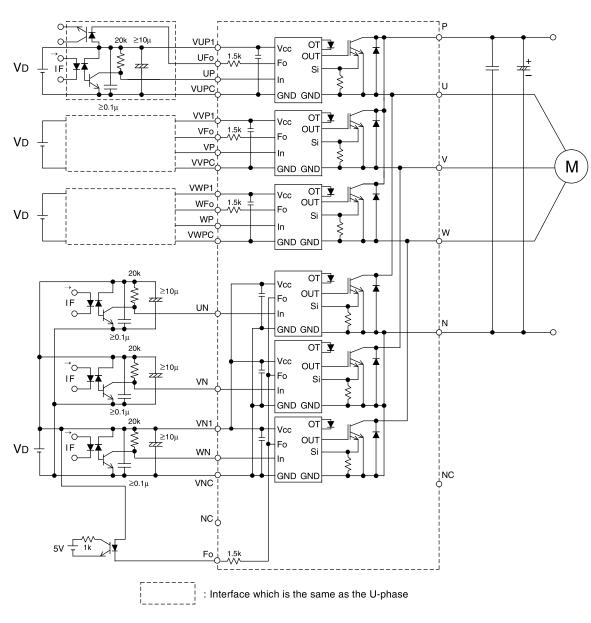


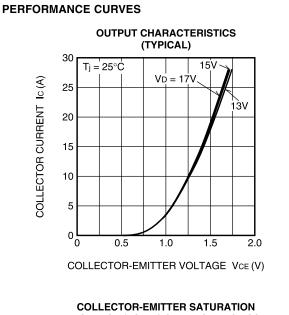
Fig. 8 Application Example Circuit

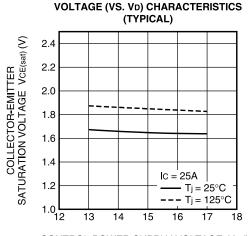
NOTES FOR STABLE AND SAFE OPERATION ;

- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- •Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: tPLH, tPHL $\leq 0.8\mu$ s, Use High CMR type.
- Slow switching opto-coupler: CTR > 100%
- •Use 4 isolated control power supplies (VD). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- •Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.
- •Use line noise filter capacitor (ex. 4.7nF) between each input AC line and ground to reject common-mode noise from AC line and improve noise immunity of the system.

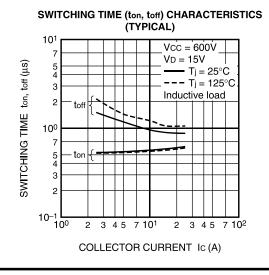


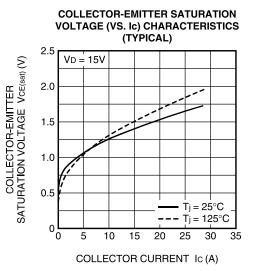
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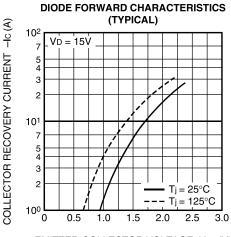




CONTROL POWER SUPPLY VOLTAGE VD (V)

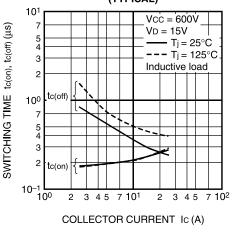




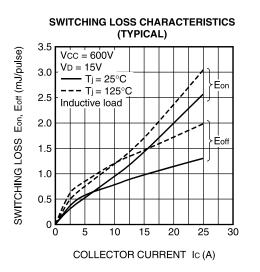


EMITTER-COLLECTOR VOLTAGE VEC (V)

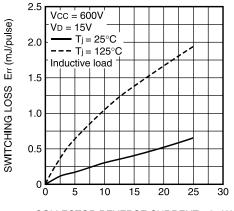
SWITCHING TIME (tc(on), tc(off)) CHARACTERISTICS (TYPICAL)



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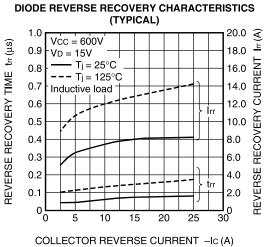


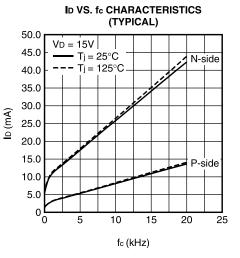
SWITCHING RECOVERY LOSS CHARACTERISTICS (TYPICAL)



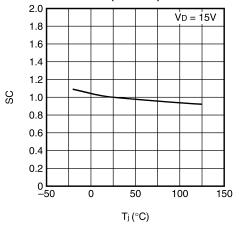
COLLECTOR REVERSE CURRENT -Ic (A)

UV TRIP LEVEL VS. Ti CHARACTERISTICS (TYPICAL) 20 - ÚVt 18 ––– UVr 16 14 12 UVt/UVr 10 8 6 4 2 0 **∟** −50 0 50 100 150 Tj (°C)





SC TRIP LEVEL VS. Tj CHARACTERISTICS (TYPICAL)

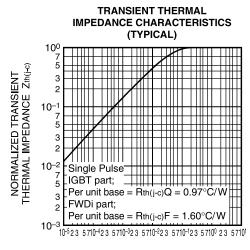




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t(sec)



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